

Dear Customer,

Please find attached our INFINEON Technologies PCN:

Transfer of wafer fab from Newport, Wales to Silicon Foundry

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **22-August-2016**.
- Infineon aligns with the widely-recognized JEDEC STANDARD “**JESD46**“, which stipulates:
“**Lack of acknowledgment of the PCN within 30 days constitutes acceptance of the change.**”

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG
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Chairman of the Supervisory Board: Wolfgang Mayrhuber
Management Board: Dr. Reinhard Ploss (CEO), Dominik Asam, Dr. Helmut Gassel, Jochen Hanebeck
Registered Office: Neubiberg Commercial Register
Amtsgericht München HRB 126492

Transfer of wafer fab from Newport, Wales to Silicon Foundry

► Products affected:

Sales Name	SP N°	OPN	Package
AUIRFS8407-7P	SP001518052	AUIRFS8407-7P	D2PAK7P
AUIRFS8409-7P	SP001522376	AUIRFS8409-7P	D2PAK7P
AUIRFB8409	SP001521544	AUIRFB8409	TO220
AUIRFR8401	SP001518132	AUIRFR8401	DPAK

► Detailed Change Information:

Subject: Transfer of wafer fab from Newport, Wales to Silicon Foundry

Reason: As part of a manufacturing consolidation plan announced in March 2015, Infineon indicated that it would be closing the Wales Fab facility and transferring the production capability for certain parts to foundries.

Description: Transfer of wafer fab from Newport, Wales to Silicon Foundry

Site	Old	New
Fab	IFX Newport Wales Fab	TowerJazz
Material		
Passivation	Epoxy Passivation	Polyimide Passivation

► Product Identification: Wafer fab origins will not be distinguished through the external part marking or shipping labels, however, based on the assembly lot code and marked on the device. IFX internal systems will be able to trace the site of the wafer lots used to produce the final product.

► Impact of Change: No changes to form, fit, or function. The package outline remains the same. Datasheet specifications will not be changed. The package bill of material and the location for assembly and final test will not change.

► Attachments:

► Time Schedule:

Final qualification report:

Available

First samples available:

On request

Intended start of delivery:

18-January-2017